# Medium-Power Plastic NPN Silicon Transistors

These high-performance plastic devices are designed for driver circuits, switching, and amplifier applications.

#### **Features**

- Low Saturation Voltage
- Excellent Power Dissipation
- Excellent Safe Operating Area
- Complement to PNP 2N4920G
- These Devices are Pb-Free and are RoHS Compliant\*\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage 2N4921G 2N4922G 2N4923G	V <sub>CEO</sub>	40 60 80	Vdc
Collector-Emitter Voltage 2N4921G 2N4922G 2N4923G	V <sub>CB</sub>	40 60 80	Vdc
Emitter Base Voltage	V <sub>EB</sub>	5.0	Vdc
Collector Current – Continuous (Note 1)	Ic	1.0	Adc
Collector Current – Peak (Note 1)	I <sub>CM</sub>	3.0	Adc
Base Current - Continuous	Ι <sub>Β</sub>	1.0	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	30 0.24	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

The 1.0 A maximum I<sub>C</sub> value is based upon JEDEC current gain requirements.
 The 3.0 A maximum value is based upon actual current handling capability of the device (see Figures 5 and 6).

#### THERMAL CHARACTERISTICS (Note 2)

Characteristic	Symbol	Max	Unit	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	4.16	°C/W	

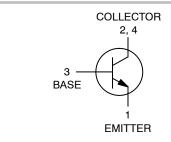
2. Recommend use of thermal compound for lowest thermal resistance. \*Indicates JEDEC Registered Data.



# ON Semiconductor®

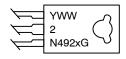
www.onsemi.com

# 1.0 AMPERE GENERAL PURPOSE POWER TRANSISTORS 40-80 VOLTS, 30 WATTS





#### **MARKING DIAGRAM**



#### **ORDERING INFORMATION**

OTIDETHING INTO OTHER PROPERTY.						
Device	Package	Shipping				
2N4921G	TO-225 (Pb-Free)	500 Units / Box				
2N4922G	TO-225 (Pb-Free)	500 Units / Box				
2N4923G	TO-225 (Pb-Free)	500 Units / Box				

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Min	Max	Unit
<u> </u>	1	I	L
VCEO(sus)	40 60 80	- - -	Vdc
Iceo	-	0.5 0.5	mAdc
	=	0.5	
ICEX	- -	0.1 0.5	mAdc
I <sub>CBO</sub>	-	0.1	mAdc
I <sub>EBO</sub>	-	1.0	mAdc
			-
h <sub>FE</sub>	40 30 10	- 150 -	-
V <sub>CE(sat)</sub>	-	0.6	Vdc
V <sub>BE(sat)</sub>	-	1.3	Vdc
V <sub>BE(on)</sub>	-	1.3	Vdc
		•	*
f⊤	3.0	_	MHz
C <sub>ob</sub>	-	100	pF
h <sub>fe</sub>	25	_	-
	VCEO(sus)  ICEO  ICEX  ICBO  IEBO  VEE(sat)  VBE(sat)  VBE(on)  fT  Cob	VCEO(sus)	VCEO(sus)  40

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: PW  $\approx$  300  $\mu$ s, Duty Cycle  $\approx$  2.0%.

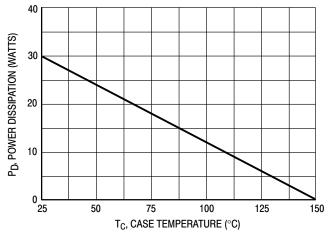


Figure 1. Power Derating

Safe Area Curves are indicated by Figure 5. All limits are applicable and must be observed.

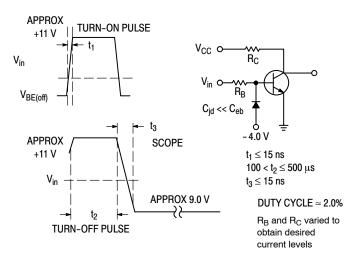


Figure 2. Switching Time Equivalent Circuit

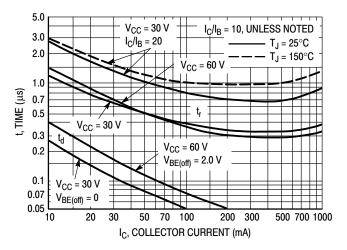


Figure 3. Turn-On Time

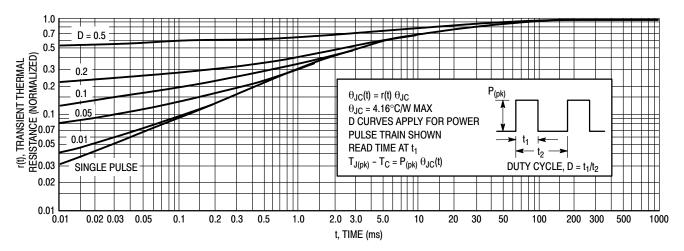


Figure 4. Thermal Response

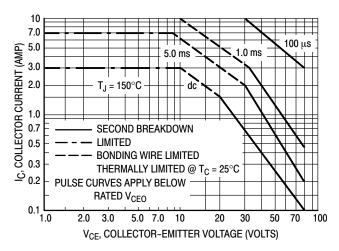


Figure 5. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  operation i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_{J(pk)} = 150^{\circ} C$ ;  $T_{C}$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ} C$ . At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

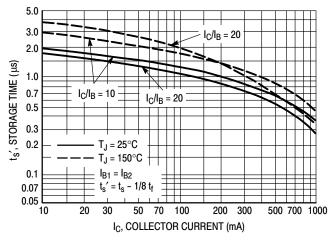


Figure 6. Storage Time

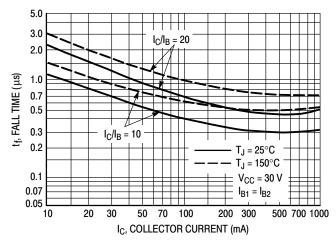
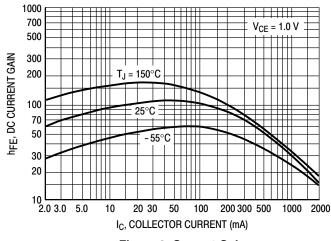


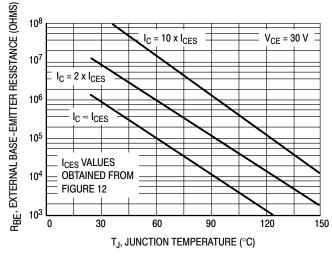
Figure 7. Fall Time



V<sub>CE</sub>, COLLECTOR-EMITTER VOLTAGE (VOLTS)  $I_{C} = 0.1 A$ 0.25 A 0.5 A 1.0 A 8.0  $T_J = 25^{\circ}C$ 0.6 0.4 0.2 0.2 0.3 20 30 50 0.5 2.0 3.0 5.0 10 100 200 IB, BASE CURRENT (mA)

Figure 8. Current Gain

Figure 9. Collector Saturation Region



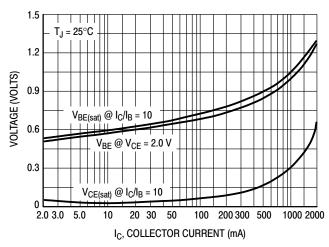
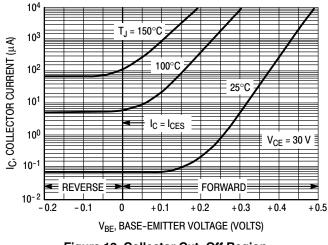


Figure 10. Effects of Base-Emitter Resistance

Figure 11. "On" Voltage



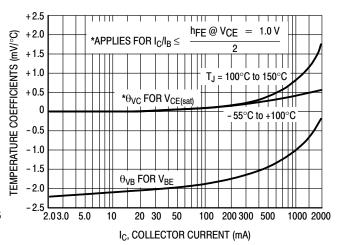
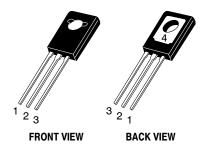


Figure 12. Collector Cut-Off Region

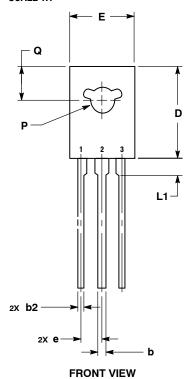
Figure 13. Temperature Coefficients

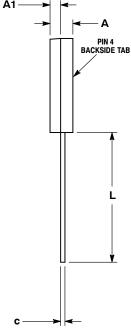


TO-225 CASE 77-09 **ISSUE AD** 

**DATE 25 MAR 2015** 





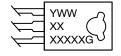


**SIDE VIEW** 

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. NUMBER AND SHAPE OF LUGS OPTIONAL.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.40	3.00		
A1	1.00	1.50		
b	0.60	0.90		
b2	0.51	0.88		
C	0.39	0.63		
D	10.60	11.10		
E	7.40	7.80		
е	2.04	2.54		
L	14.50	16.63		
L1	1.27	2.54		
P	2.90	3.30		
Q	3.80	4.20		

#### **GENERIC MARKING DIAGRAM\***



= Year

WW = Work Week

XXXXX = Device Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

2., 4.		2., 4.	CATHODE ANODE GATE	2., 4.	BASE COLLECTOR EMITTER	2., 4.	ANODE 1 ANODE 2 GATE	STYLE 5: PIN 1. 2., 4. 3.	
STYLE 6:		STYLE 7:		STYLE 8:		STYLE 9:		STYLE 10:	
PIN 1.	CATHODE	PIN 1.	MI1	PIN 1.	SOURCE	PIN 1.	GAIL	PIN 1.	SOURCE
2., 4.	GATE	2., 4.	GATE	2., 4.	GATE	2., 4.	DRAIN	2., 4.	DRAIN
3.	ANODE	3.	MT 2	3.	DRAIN	3.	SOURCE	3.	GATE

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